

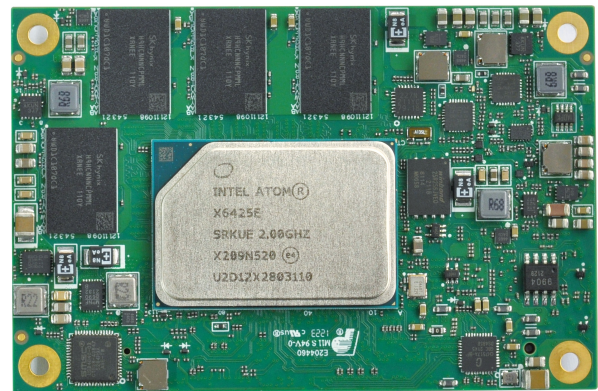
COM-x6425E

COM Express® Mini Size Type 10 Module with
Intel® Atom™ x6000E Series Processor SOC

产品功能

- ◆ 单,双, 四核 Intel® Atom™ X6000E SOC 处理器
- ◆ 板载 16GB DDR4 内存
- ◆ 板载 32-256G eMMC 电子盘 (可以选择)
- ◆ 1 个双通道 18/24Bit LVDS 显示接口
- ◆ 2 个 RS232 接口
- ◆ 1 个 CRT 和 HDMI 显示接口
- ◆ 3 个 PCIe x1, 1 个 2.5G GbE
- ◆ 2 个 SATA , 4 个 USB2.0, 2 个 USB3.0
- ◆ 工作温度: -25°C to +75°C

扩展温度: -40°C to +85°C



技术参数

核心系统

CPU	Single, dual, quad-core Intel® Atom™ X6000E X6425E 2.0 GHz (3.0GHz 12W (4C)) X6413E 1.9 GHz (3.0GHz 9W (4C)) X6211E 1.3 GHz (3.0GHz 6W (2C)) X6200FE 1.0 GHz (3.0GHz 4.5W (2C)) no GPU
Memory	DDR4, memory up to 16GB
Embedded BIOS	AMI EFI with CMOS backup in 8MB SPI BIOS
Cache	TBC
Expansion Busses	3 PCI Express x1 Gen2 (AB): lanes 0/1/2; Optional PCIe x4 (lose GbE) LPC bus, SMBus (system), I ² C (user)

显示

GPU Feature	11th Intel® graphics Core architecture
Display Interface LVDS/eDP /CRT	One DDI channel supporting DisplayPort/HDMI/DVI Double channel 18/24-bit LVDS eDP support(optional) CRT support

声卡

Chipset	Intel® HD Audio integrated in SOC
Audio Codec	Located on carrier COM-E3845-X 底板

网络

Intel® MAC/PHY Interface	Intel® i225 (MAC/PHY) Ethernet controller 100M/1000M/2.5G GbE connection
-----------------------------	---

I/O 接口

USB	2xUSB 3.0 4x USB 2.0
SATA	2 SATA
Serial	2 UART
eMMC	32G to 256 GB
GPIO	4 GPO and 4 GPI

扩展 I/O

Standard Input	On carrier if needed (standard support for SMC3114)
----------------	---

电源

Standard Input	ATX = 12V±2% / 5Vsb ±5% or AT = 12V±2%
Wide Input	ATX = 5-20V / 5Vsb (standard temp. only) ATX = 5-20V / 5Vsb (standard temp. only)
Management	ACPI 4.0 compliant, Smart Battery support
Power States	C0, C1, C1E, C4, C6 S0, S3, S4, S5 (Wake on USB S3/S4, WOL S3/S4/S5)
ECO mode	Supports deep S5 (ECO mode) for power saving

机械尺寸及环境

Form Factor	PICMG COM.0: Rev 2.1 Type 10
Dimension	Mini size: 84 mm x 55 mm
Operating Temperature	Standard: -25°C to +75°C Extreme Rugged: -40 to +85°C
Humidity	5-90% RH operating, non-condensing 5-95% RH storage (operating with conformal coating) MIL-STD-202F, Method 213B, Table 213H, Condition A and Method 214A, Table 214-I Condition D
HALT	Thermal Stress, Vibration Stress, Thermal Shock and Combined Test

操作系统支持

Standard Support	Wi10/64-bit, Win10 IOT 64-bit, Yocto Linux 64-bit VxWorks 64-bit, Ubuntu (TPC)
Extended Support	Yocto project based Linux 64-bit



开发工具

Year	Percentage of respondents
2013	~85%
2014	~65%
2015	~68%

<http://www.hsem.com.cn>